MA2SV15

Silicon epitaxial planar type

For VCO

Features

- Good linearity and large capacitance-ratio in $C_D V_R$ relation
- Small series resistance r_D
- SS-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	6	V
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 to +150	°C



Marking Symbol: 6A

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

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Parameter	Symbol	Conditions	Min	Тур	Max	Unit		
Reverse current	I _R	$V_R = 5 V$			10	nA		
Diode capacitance	C _{D(0.5V)}	$V_{\rm R} = 0.5 \text{ V}$ = 1 MHz	7.30		7.91	pF		
	C _{D(2.5V)}	$V_{R} = 2.5 V, f = 1 MHz$	2.98		3.23			
Capacitance ratio	C _{D(0.5V)} /C _{D(2.5V)}		2.35		2.55			
Series resistance *	r _D	$V_{R} = 1$ V, f = 470 MHz			0.45	Ω		

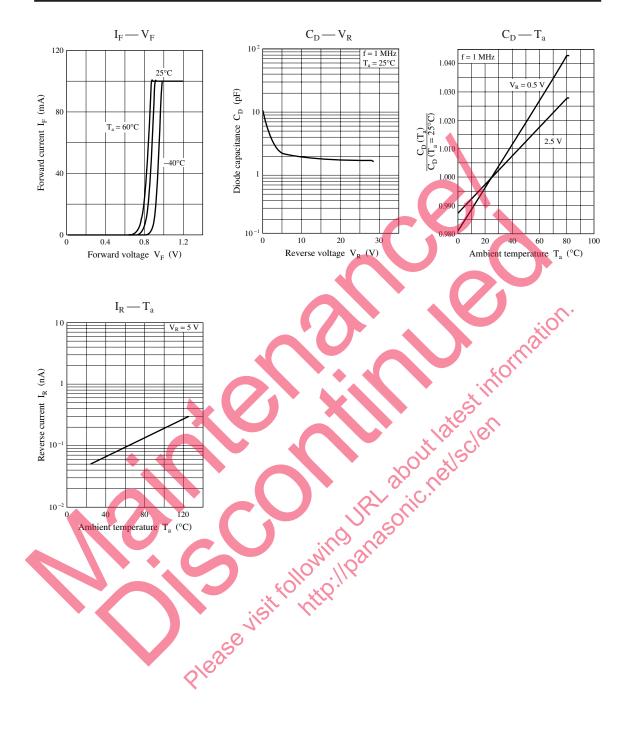
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 470 MHz.

3. *: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER

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